

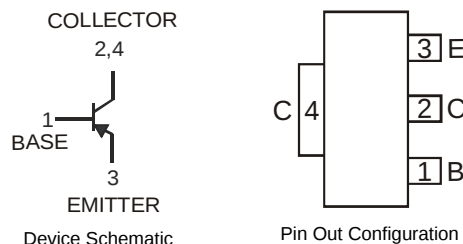
LOW $V_{CE(SAT)}$ PNP SURFACE MOUNT TRANSISTOR

Features

- Epitaxial Planar Die Construction
- Ideally Suited for Automated Assembly Processes
- Ideal for Medium Power Switching or Amplification Applications
- **Lead Free By Design/RoHS Compliant (Note 1)**
- **"Green" Device (Note 2)**

Mechanical Data

- Case: SOT-223
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Finish — Matte Tin annealed over Copper leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.115 grams (approximate)

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-60	V
Collector-Emitter Voltage	V_{CEO}	-50	V
Emitter-Base Voltage	V_{EBO}	-6	V
Peak Pulse Current	I_{CM}	-5	A
Continuous Collector Current	I_C	-3	A
Base Current	I_B	-1	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 3) @ $T_A = 25^\circ\text{C}$	P_D	1	W
Thermal Resistance, Junction to Ambient Air (Note 3) @ $T_A = 25^\circ\text{C}$	$R_{\theta JA}$	125	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

- Notes:
1. No purposefully added lead.
 2. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 3. Device mounted on FR-4 PCB; pad layout as shown on page 4 or in Diodes Inc. suggested pad layout document AP02001, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Conditions
OFF CHARACTERISTICS (Note 4)						
Collector-Base Cutoff Current	I _{CBO}	—	—	-100	nA	V _{CB} = -50V, I _E = 0
Emitter-Base Cutoff Current	I _{EBO}	—	—	-50	μA	V _{CB} = -50V, I _E = 0, T _A = 150°C
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-50	—	—	V	V _{EB} = -5V, I _C = 0
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	-50	—	—	V	I _C = -100μA
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	-5	—	—	V	I _E = -100μA
ON CHARACTERISTICS (Note 4)						
DC Current Gain	h _{FE}	200	—	—	—	V _{CE} = -2V, I _C = -0.5A
		200	—	—		V _{CE} = -2V, I _C = -1A
		100	—	—		V _{CE} = -2V, I _C = -2A
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	—	—	-100	mV	I _C = -0.5A, I _B = -50mA
		—	—	-180		I _C = -1A, I _B = -50mA
		—	—	-300		I _C = -2A, I _B = -200mA
Equivalent On-Resistance	R _{CE(SAT)}	—	67	150	mΩ	I _E = -2A, I _B = -200mA
Base-Emitter Saturation Voltage	V _{BE(SAT)}	—	—	-1.2	V	I _C = -2A, I _B = -200mA
Base-Emitter Turn-on Voltage	V _{BE(ON)}	—	—	-1.1	V	V _{CE} = -2V, I _C = -1A
SMALL SIGNAL CHARACTERISTICS						
Transition Frequency	f _T	100	—	—	MHz	V _{CE} = -5V, I _C = -100mA, f = 100MHz
Output Capacitance	C _{obo}	—	—	40	pF	V _{CB} = -10V, f = 1MHz

Notes: 4. Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤2%.

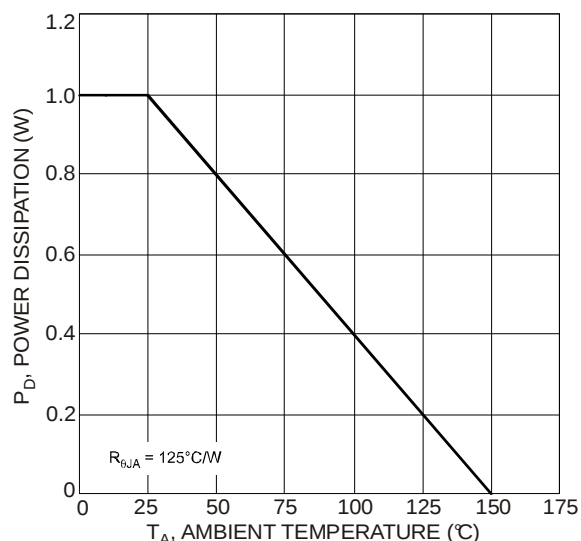


Fig. 1 Power Dissipation vs. Ambient Temperature (Note 3)

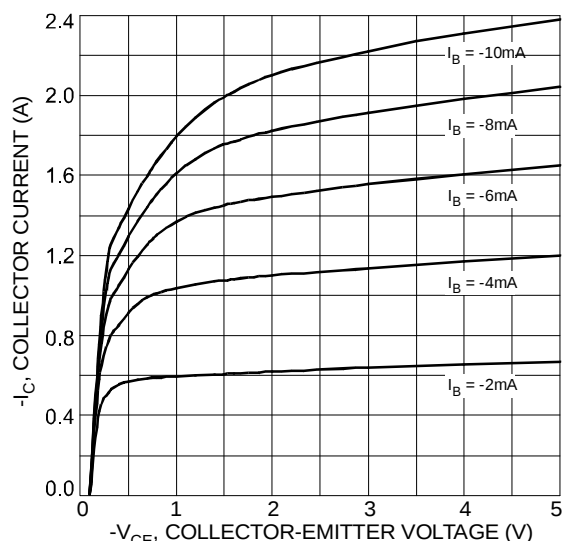
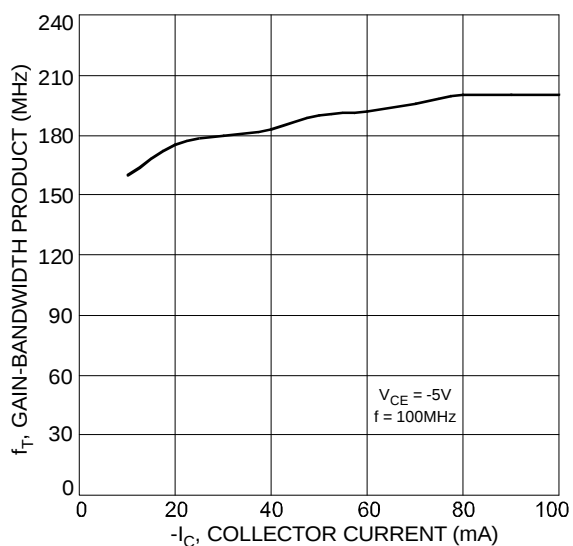
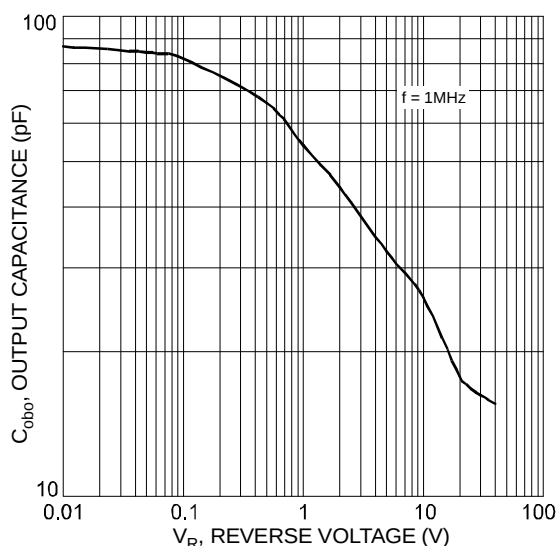
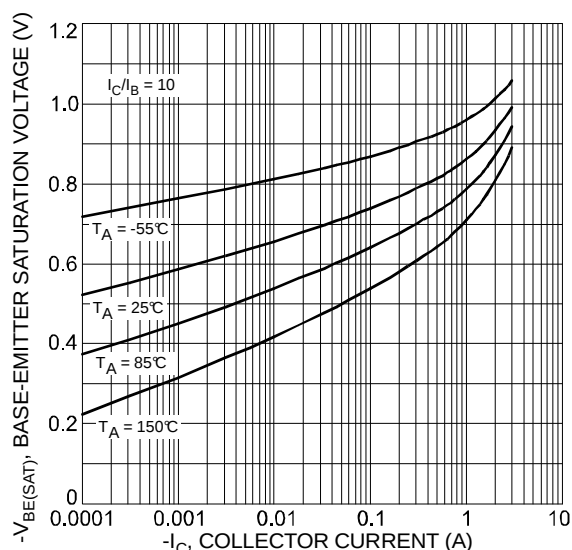
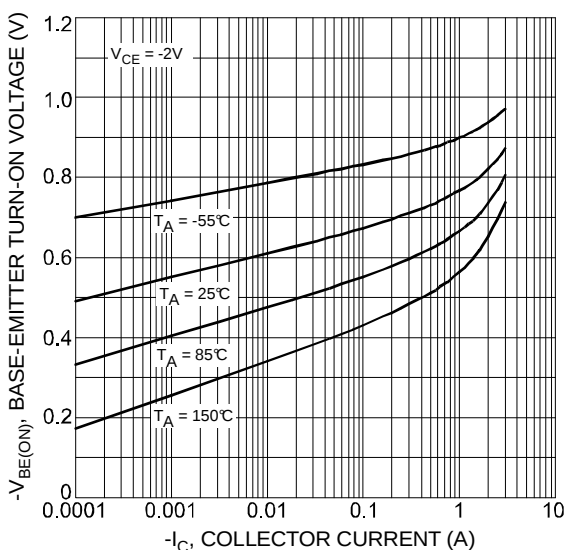
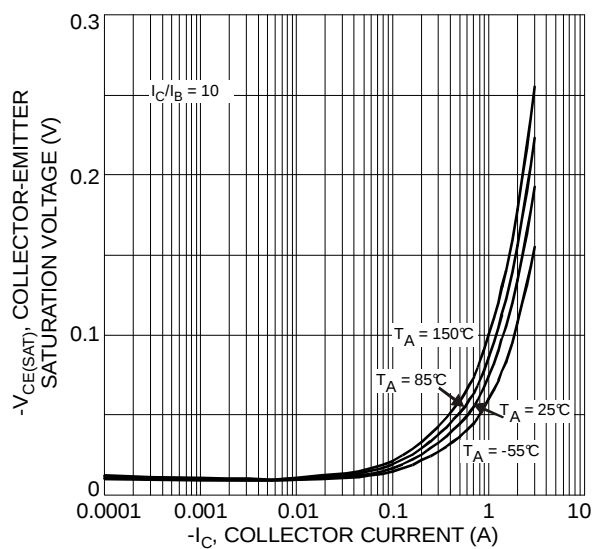
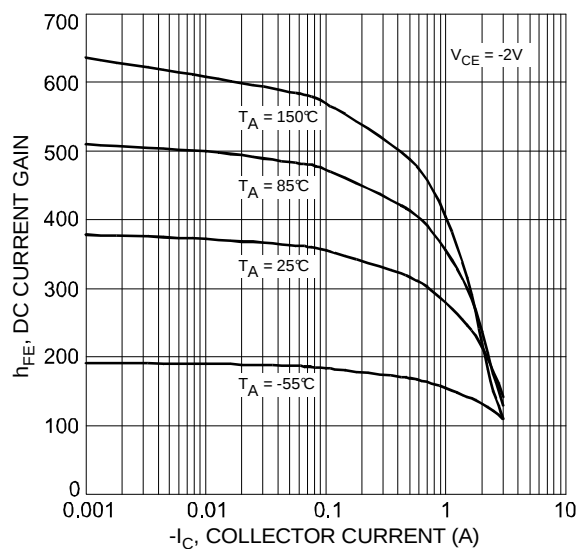


Fig. 2 Typical Collector Current vs. Collector-Emitter Voltage



Ordering Information (Note 5)

Part Number	Case	Packaging
DPLS350E-13	SOT-223	2500/Tape & Reel

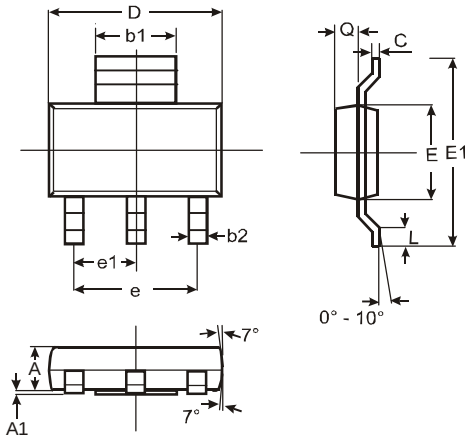
Notes: 5. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



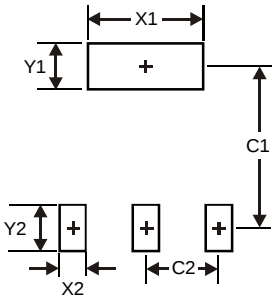
P35 = Product Type Marking Code
DII = Manufacturer's Code Marking
YWW = Date Code Marking
Y = Last digit of year (ex: 7 = 2007)
WW = Week code 01 - 52

Package Outline Dimensions



SOT-223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b1	2.90	3.10	3.00
b2	0.60	0.80	0.70
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	—	—	4.60
e1	—	—	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
X1	3.3
X2	1.2
Y1	1.6
Y2	1.6
C1	6.4
C2	2.3

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